

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 09107129
PUBLICATION DATE : 22-04-97

APPLICATION DATE : 09-10-95
APPLICATION NUMBER : 07261651

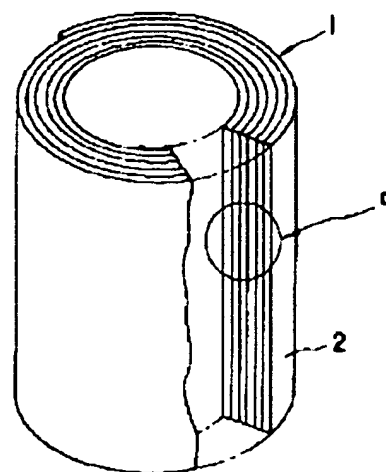
APPLICANT : SHARP CORP;

INVENTOR : TOMITA KOJI;

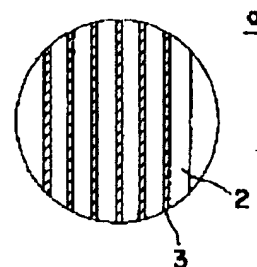
INT.CL. : H01L 35/32

TITLE : SEMICONDUCTOR DEVICE AND ITS
MANUFACTURING METHOD

(A)



(B)



ABSTRACT : PROBLEM TO BE SOLVED: To manufacture a compact and high-performance semiconductor device by easily fabricating the semiconductor device in an arbitrary shape.

SOLUTION: A semiconductor device consists of a flexible film-shaped insulation substrate 2 such as polyimide and Teflon and a semiconductor 3 for thermoelectric conversion being formed on the entire surface of its single surface and the semiconductor 3 is fabricated by rolling the film-shaped insulation substrate 2. The semiconductor 3 is either a P-type thermoconversion semiconductor or N-type thermoconversion semiconductor in ultra-lattice structure by an ultra-thin film.

COPYRIGHT: (C)1997,JPO